

Package Material Composition and Mass Calculation

Joel Cheng 2011/1/25 Provided By : Date : Rev. :

Customer : Package : Device Type : Die Size(mm) :

Total Pkg. Wt (g):

Total Pkg. Wt (g).	name	material composition	CAS No.	%	mg.(ave)	mg.	%	РРМ	SGS Report	Due date (calibration within 1 year)	MSDS Report	Due date (calibration within 3 year)
Mold Compound	CEL-9240					32.3375	42.166%	421,663				
		Epoxy Resin#1	Trade Secret	0.4-2.4%	0.45273		0.590%	5,903				
		Epoxy Resin#2	Trade Secret	0.1-0.6%	0.12935		0.169%	1,687				
		Epoxy resin#3	Trade Secret	2-6%	1.29350		1.687%	16,867				
		Carbon black	1333-86-4	Approx 0.2%	0.06468		0.084%	843				
		Silica	60676-86-0	82-94%	29.26544		38.160%	381,605				
		Hardener	Trade Secret	2-5%	1.13181		1.476%	14,758				
Leadframe	C194_Silver					38.44	50.118%	501,177				
		Copper (Cu)	7440-50-8	90~98%	37.09027		48.364%	483,636				
		Others	Trade Secret	<1%	0.38436		0.501%	5,012				
		Plated Silver (Ag)	7440-22-4	0.120-12.480%	0.96089		1.253%	12,529				
Die_1	Silicon	Silicon	7440-21-3	100%		4.13	5.382%	53,825				
Die Attach_1	EN4900G					0.59	0.775%	7,747				
		Silver	7440-22-4	72-82%	0.44263		0.577%	5,772				
		Acrylic resin	Trade Secret	6-11%	0.05050		0.066%	659				
		Polybutadiene derivative	Trade Secret	2-9%	0.02377		0.031%	310				
		Butadiene copolymer	Trade Secret	<2%	0.01188		0.015%	155				
		Epoxy resin	Trade Secret	1-4%	0.01485		0.019%	194				
		Acrylate	Trade Secret	3-8%	0.03268		0.043%	426				
		Peroxide	Trade Secret	<1%	0.00594		0.008%	77				
		Additive	Trade Secret	<2%	0.01188		0.015%	155				
Wire	Cu wire					0.14897	0.194%	<u>1,943</u>				
		Cu	7440-50-8	99.99%	0.14896		0.1942%	1,942				
		Ion Impurities	Trade Secret	0.01%	0.00001		0.0000%	0				
External Plating	Sn plating					1.04646	1.365%	13,645				
		Sn	7440-31-5	100%	1.04646		1.365%	13,645				
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- DISCLAIMER

 The above material declaration can be used only as reference in identifying the Hazardous material content of the product.

 ASE does not guarantee the Material composition accuracy as it is based on the data provided by outside sources and has not been validated.

 This material declaration does not include data from any active and passive component assembled in the package.

 Due to Leadframe and substrate is belong "re-make product" by other homogeneous material, so it's composition will be different with MSDS